IN THE ABSTRACT:

Please delete the present Abstract of the Disclosure and replace it with the following new Abstract of the Disclosure:

A Dry-Film resist [DF] formed of, for example, a photosensitive film is stacked on the electroconductive material and these portions, other than a projection electrode formation area, formed on a wiring board's electrode serving as a portion of a circuit pattern are masked with a mask. After this, the wiring board is exposed to light and, after the removal of the mask, a development process is performed, thus eliminating the Dry-Film resist [DF] on the wiring board at the portion other than the projection electrode formation area. Then the electroconductive material of the wiring board is etched under an etching process to provide a projection electrode having a bump with a pointed tapering end in vertical cross-section. Finally, the wiring board is exposed to a Dry-Film resist [DF] elimination solution to remove remaining Dry-Film resist [DF] from the projection electrode. And a plating process is performed on the electroconductive material to form a plated layer and hence complete the projection electrode.